

ELECTRONIC ASSEMBLY WITH INTEGRATED IO AND POWER CONTACTS

ABSTRACT

In some example embodiments, an integrated circuit, electronic assembly and method provide a current path for supplying power to a processor. As an example, the integrated circuit includes a base having power contacts that extend from an upper surface of base. The integrated circuit further includes a substrate
5 that is mounted to the upper surface of the base to electrically couple the substrate to the base. A die is mounted on a substrate such that the die is electrically coupled to the substrate. The power contacts on the upper surface of the base engage a daughterboard so that the die is able to receive power from a voltage source mounted on the daughterboard through the power contacts on the upper surface of
10 the base.

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